

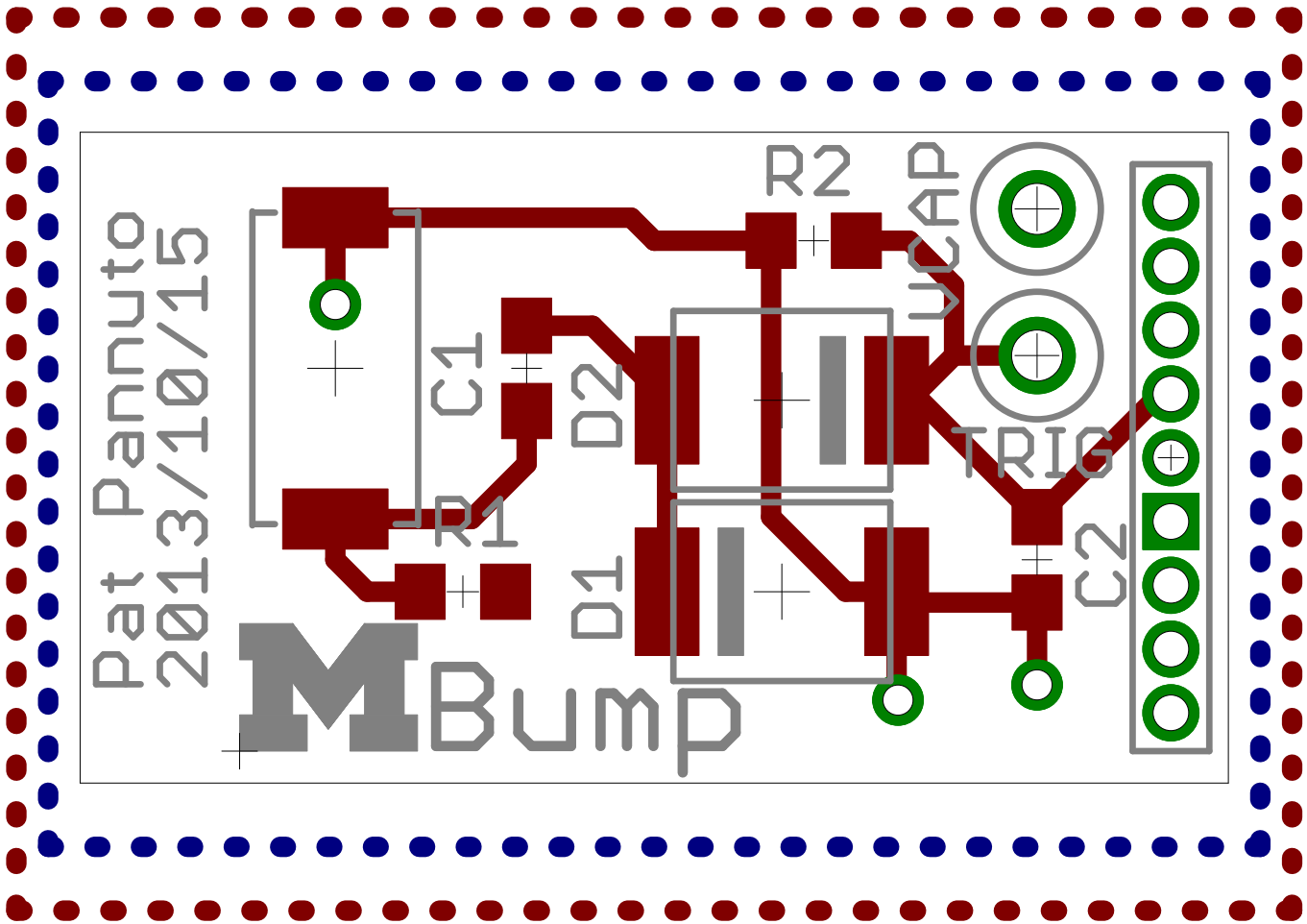
M Bump

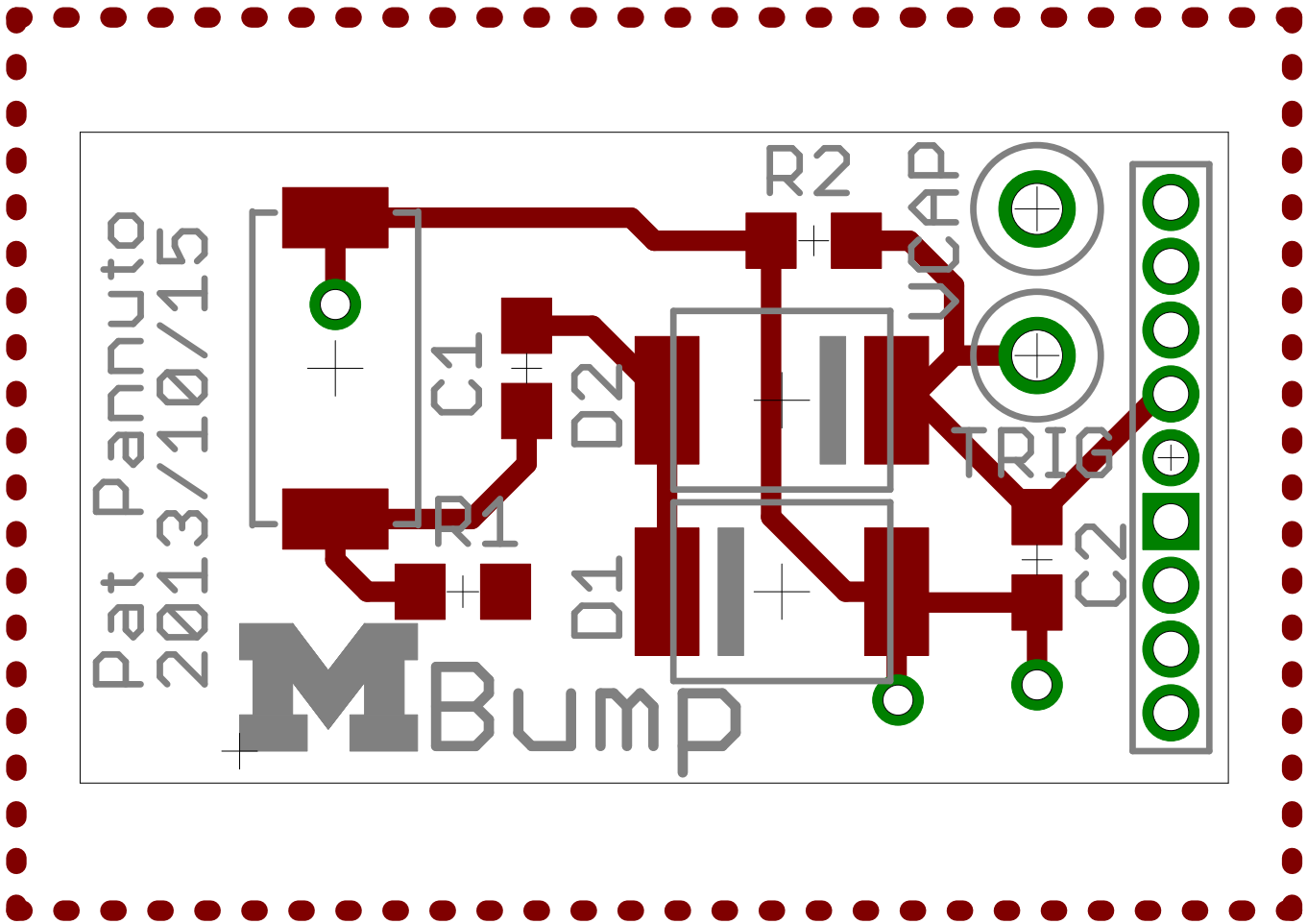
REV:
A

Author: Pat Pannuto

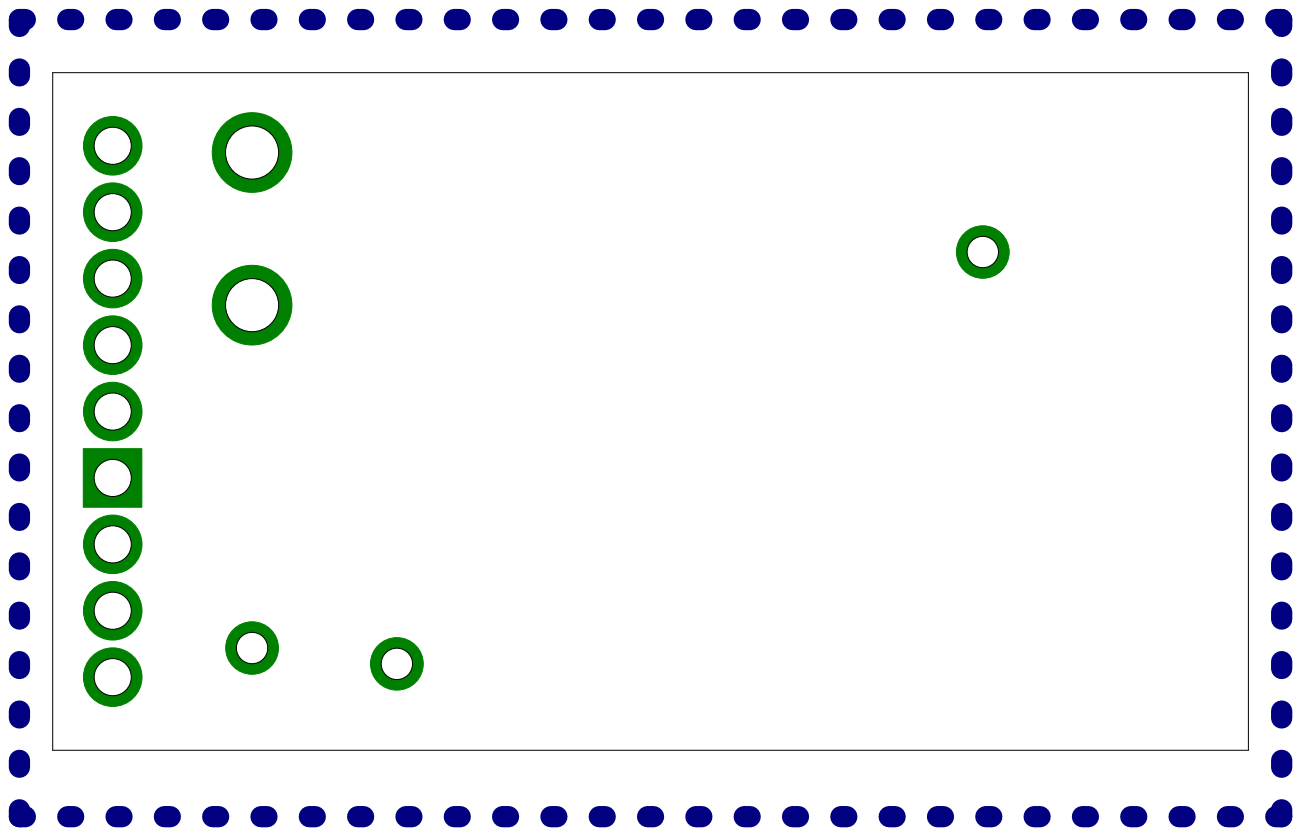
Date: 1/9/14 5:38 PM

Sheet: 1/1

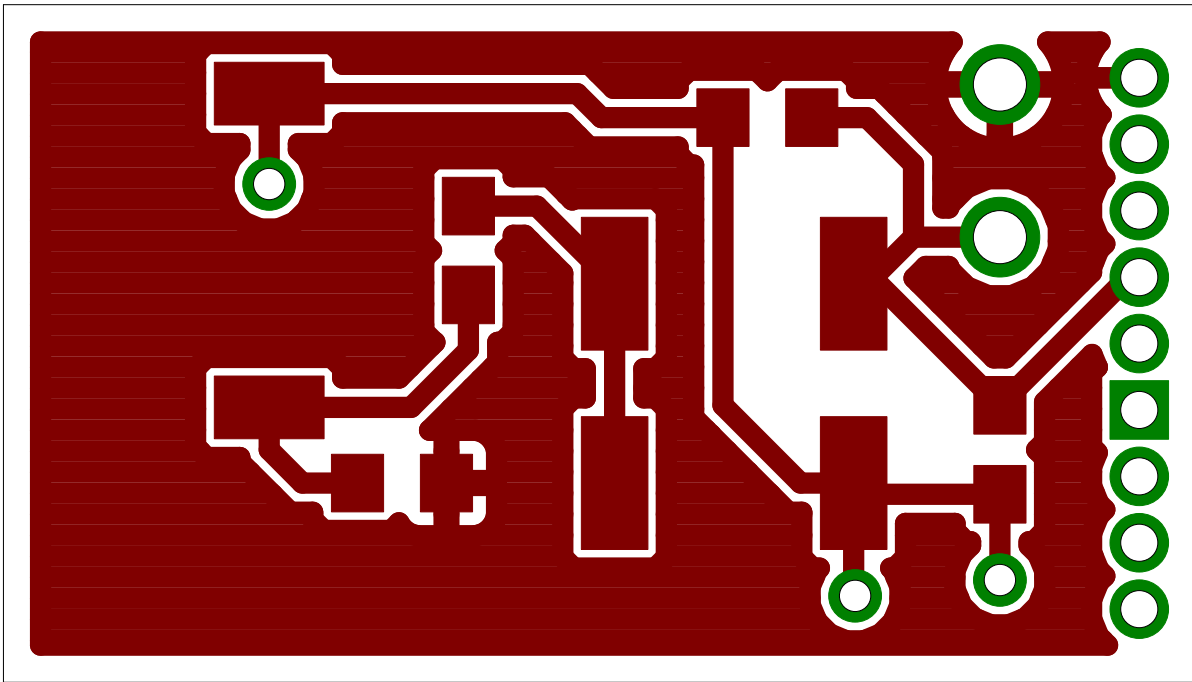




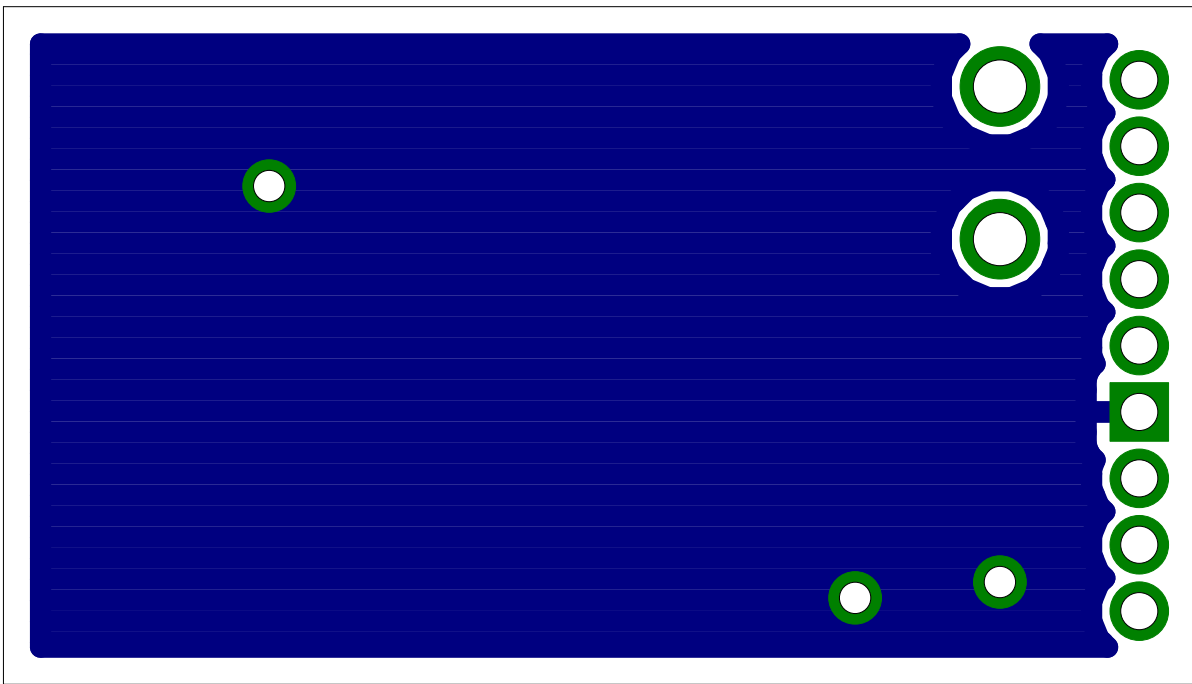
Bottom Layer

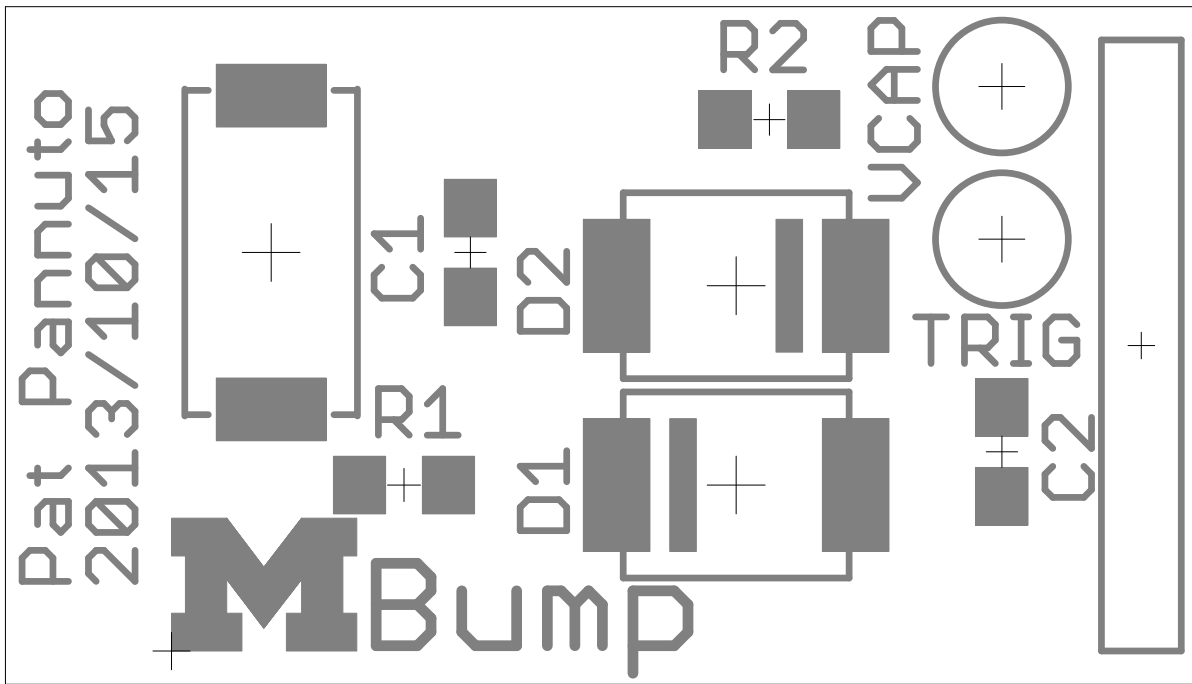


Top Copper Layer

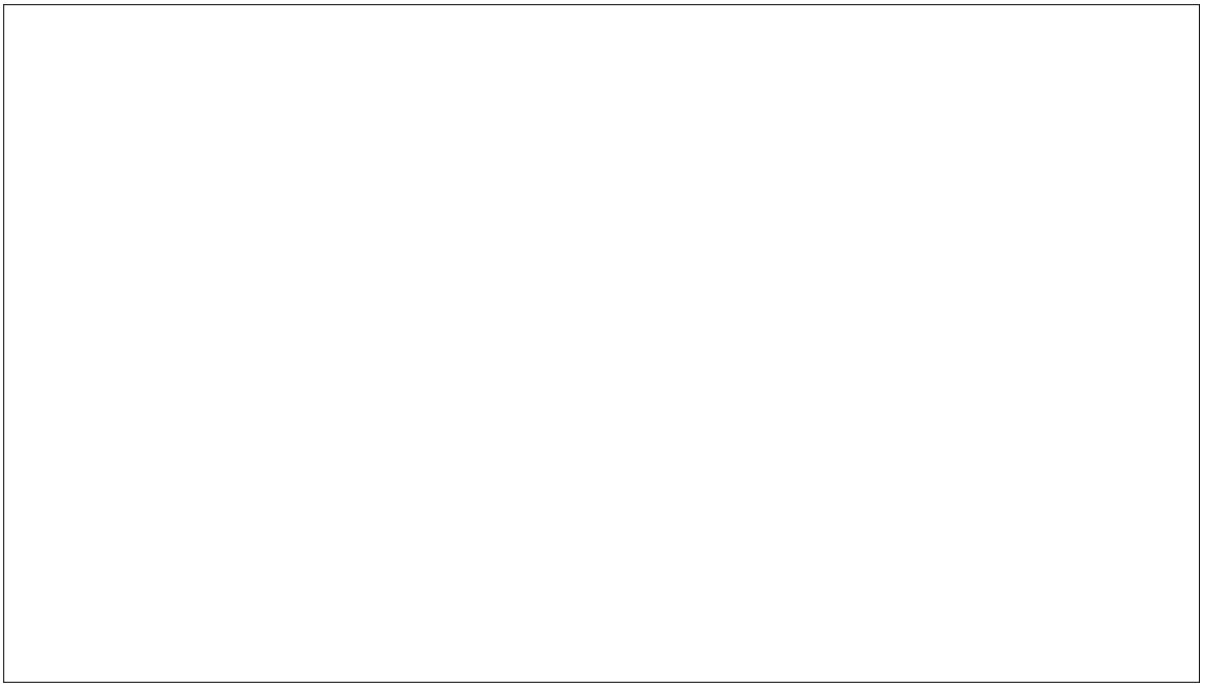


Bottom Copper Layer

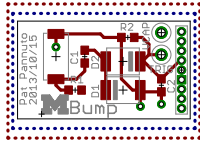




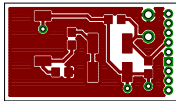
Bottom Paste Layer with Silkscreen



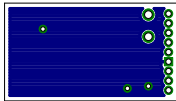
Top and Bottom Layers 1:1 Scale



Top Layer 1:1 Scale



Bottom Copper Layer 1:1 Scale



Sheet1

Qty	Value	Device	Package	Parts
2	LSM115J	LSM115J	D0-214BA	D1, D2
1	IMPULSE_GECKO_HEADER	IMPULSE_GECKO_HEADER	HEADER1X9/0.05IN	J1
1		Resistor	R0603	R1
1		Resistor	R0603	R2
1		Capacitor	C0603	C1
1		Capacitor	C0603	C2
1		SQ-SEN-200	SQ-SEN-200	VS1

Sheet1

Description

Diode Schottky 15V 1A
Header on the impulse EPIC-esque board.

DIGIKEY

LSM115JE3/TR13CT-ND

Vibration Sensors (Unstable Balls)